

# DC Input 4-Pin Mini-Flat DMC-Isolator® **Phototransistor Optocoupler**

### Features

- High isolation 3750 VRMS
- Patented coplanar structure DMC-Isolator®
- Various CTR selection available
- DC input with transistor output
- Operating temperature range 55 °C to 110 °C
- External Creepage ≥ 5.0mm
- Distance Through Isolation  $\geq 0.4$ mm
- Clearance Distance ≥ 5.0mm
- **RoHS and REACH Compliance**
- Halogen Free Compliance
- MSL class 1
- **Regulatory Approvals** 
  - ✓ UL - UL1577 (E364000)
  - ~ VDE - EN60747-5-5 (VDE0884-5)
  - ✓ CQC - GB4943.1, GB8898 (19001231775)
  - IEC62368 (FI/41119)  $\checkmark$

# **Package Outline**

# Description

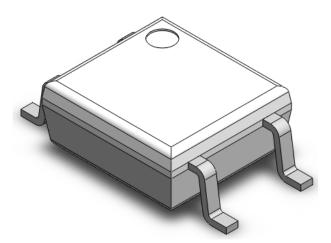
The CT357 series of general purpose optocoupler consists of a photo transistor optically coupled to an Infrared-emitting diode in a 4-lead Mini-Flat DMC-Isolator® package with bending option.

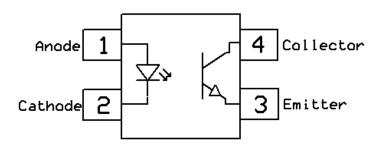
**CT357 Series** 

# **Applications**

- **DC-DC** Converters
- Programmable controllers
- **Telecommunication equipment**
- Hybrid substrates that require high density mounting









### Absolute Maximum Ratings $T_A = 25^{\circ}$ C, unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	3750	V <sub>RMS</sub>	
T <sub>OPR</sub>	Operating temperature	-55 ~ +110	٥C	
Tstg	Storage temperature	-55 ~ +150	°C	
Tsol	Soldering temperature (For 10 seconds)	260	°C	
Ртот	Total power dissipation	200	mW	
Emitter				
IF	Forward current	50	mA	
F(TRANS)	Peak transient current (≤1µs P.W,300pps)	1	А	
VR	Reverse voltage	6	V	
PD	Power dissipation	70 m <sup>1</sup>		
Detector	-	·		·
Pc	Power dissipation	150	mW	
BVCEO	Collector-Emitter Breakdown Voltage	80	V	
BVECO	Emitter-Collector Breakdown Voltage	7	V	
lc	Collector Current	50	mA	



### **Electrical Characteristics** $T_A = 25^{\circ}C$ , unless otherwise specified

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	IF=10mA	-	1.24	1.4	V	
I <sub>R</sub>	Reverse Current	$V_R = 6V$	-	-	5	μA	
CIN	Input Capacitance	f= 1MHz	-	10	250	pF	

#### **Detector Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
B <sub>VCEO</sub>	Collector-Emitter Breakdown	Ic= 100μA	80	-	-	V	
BVECO	Emitter-Collector Breakdown	I <sub>E</sub> = 100μA	7	-	-	V	
ICEO	Collector-Emitter Dark Current	V <sub>CE</sub> = 20V, I <sub>F</sub> =0mA	-	-	100	nA	

#### **Transfer Characteristics**

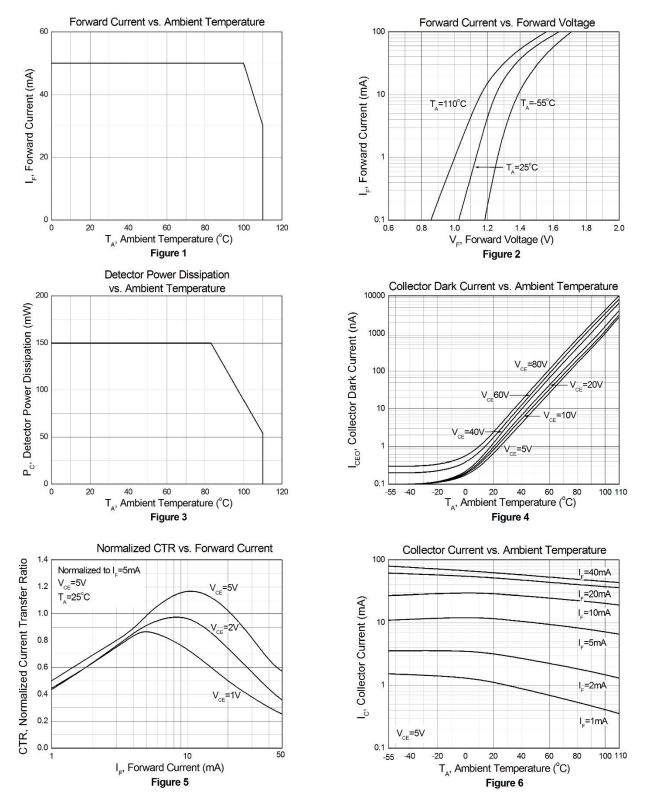
Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
		CT357		50	•	600		
		CT357A	IF= 5mA, V <sub>CE</sub> = 5V	80	-	160	%	
CTR	(	CT357B		130	-	260		
		CT357C		200	-	400		
		CT357D		300	-	600		
Maria	Collector-Emitter Saturation		I⊧= 20mA, Ic= 1mA	_	0.06	0.2	V	
Vce(sat)	Voltage		IF= 20MA, IC= TMA	-	0.00	0.2	V	
RIO	Isolation Resistance		$V_{IO}$ = 500 $V_{DC}$ , 40 ~ 60% R.H.	5x10 <sup>10</sup>	-	-	Ω	
Сю	Isolation Capacitance		f= 1MHz	-	0.5	1	pF	

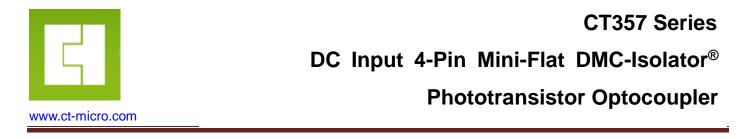
#### **Switching Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
tr	Rise Time	$1 = 2mA$ $1/2 = 21/B_1 = 1000$	-	6	18	0	
t <sub>f</sub>	Fall Time	I <sub>C</sub> = 2mA, V <sub>CE</sub> = 2V, R <sub>L</sub> = 100Ω	-	8	18	μs	

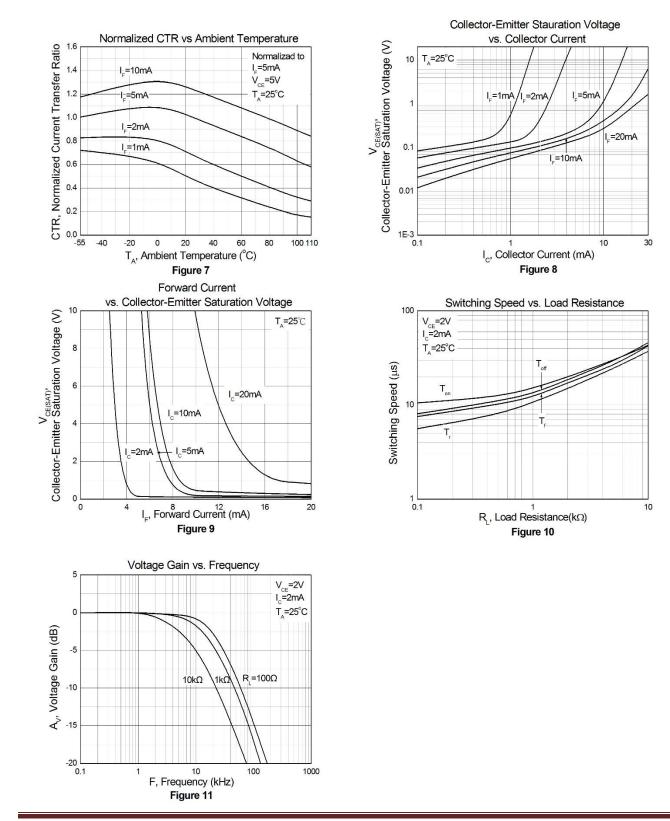


### Typical Characteristic Curves $T_A = 25^{\circ}C$ , unless otherwise specified





#### Typical Characteristic Curves $T_A = 25^{\circ}C$ , unless otherwise specified (Continued)





# **Test Circuit**

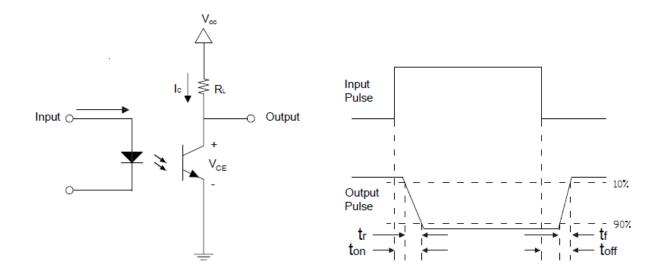
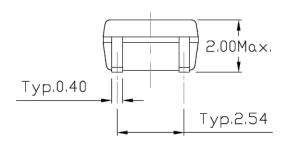
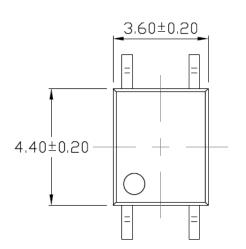


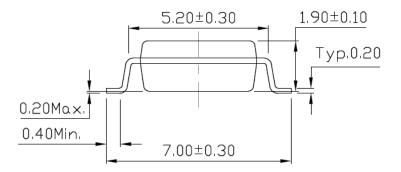
Figure 12: Switching Time Test Circuit

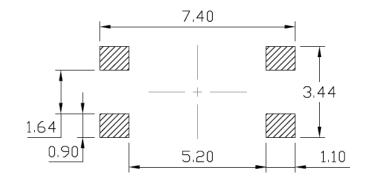


### Package Dimension Dimensions in mm unless otherwise stated









# **Marking Information**



Note:

-		
	СТ	: Denotes "CT Micro"
	357	: Part Number
	Х	: CTR Rank (Blank, A, B, C or D)
	V	: VDE Safety Mark (Blank or V)
	Y	: One Digit Year Code

- WW : Two Digit Work Week
  - : Manufacturing Code

Κ



# **Ordering Information**

# CT357X(V)(Z)

СТ	= Denotes "CT Micro"

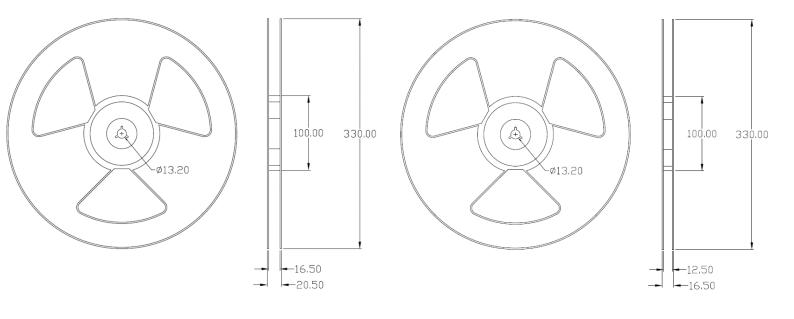
- 357 = Part Number
- X = CTR Rank Option (Blank, A, B, C or D)
- V = VDE Safety Mark Option (Blank or V)
- Z = Tape and Reel Option (T1, T2, T3 or T4)

Option	Description	Quantity
T1	T1 Surface Mount Lead Forming – With Option 1 Tapping	
T2	Surface Mount Lead Forming – With Option 2 Tapping	3000 Units/Reel
Т3	Surface Mount Lead Forming – With Option 3 Tapping	3000 Units/Reel
T4	Surface Mount Lead Forming – With Option 4 Tapping	3000 Units/Reel

## Reel Dimension All dimensions are in mm, unless otherwise stated

Option T1 / T2

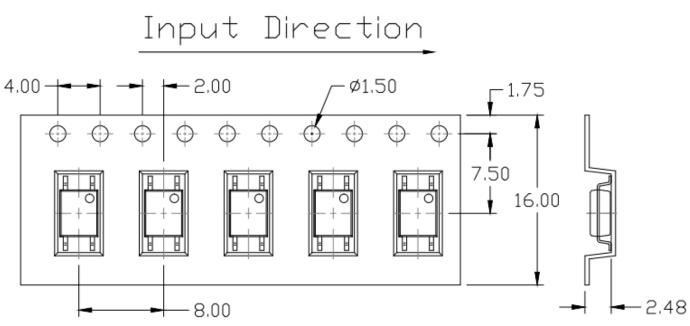
Option T3 / T4



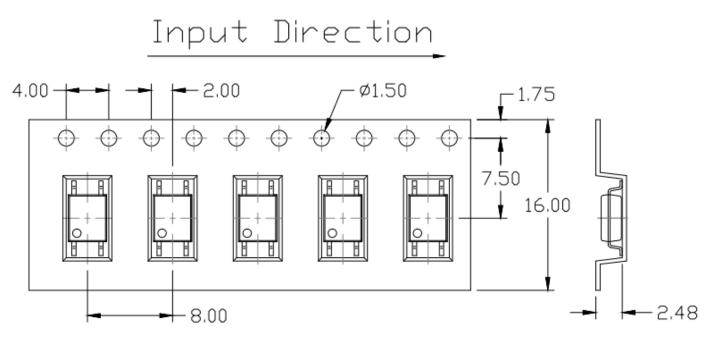


### Carrier Tape Specifications Dimensions in mm unless otherwise stated

### **Option T1**

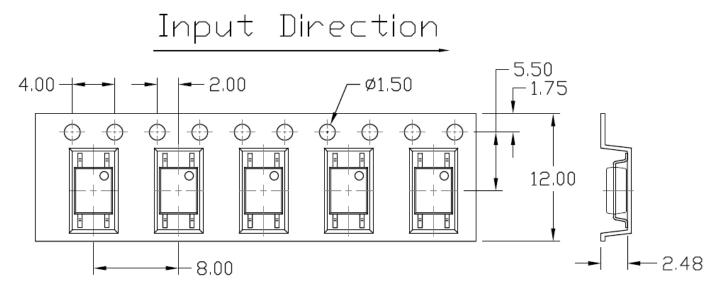


## **Option T2**

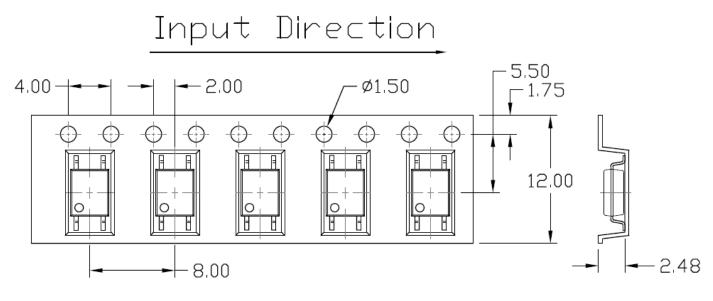




### **Option T3**



### **Option T4**





# Solderability Specification (follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

# Wave soldering (Follow the JEDEC standard JESD22-A111)

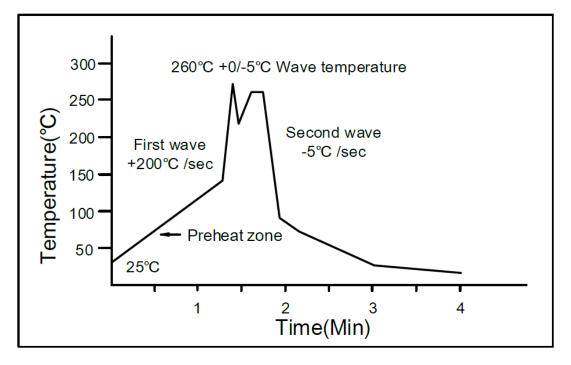
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature: 25 to 140°C.

Preheat time: 30 to 80 sec.



# Iron Soldering (follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process. One time soldering is recommended.

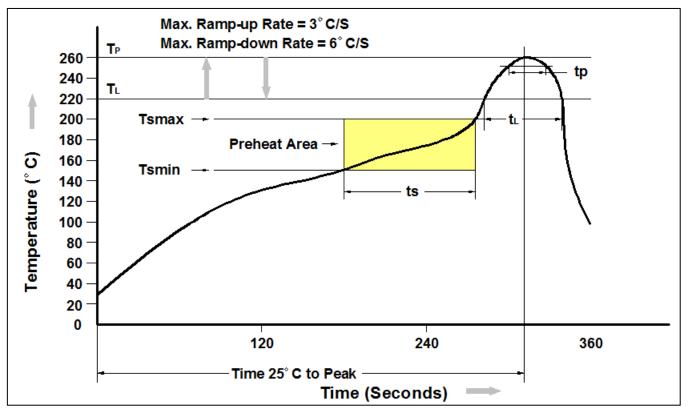
Temperature: 350±10°C

Time: 5 sec max.



**Phototransistor Optocoupler** 

# Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to tթ)	3°C/second max.
Liquidous Temperature (T∟)	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate ( $T_P$ to $T_L$ )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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